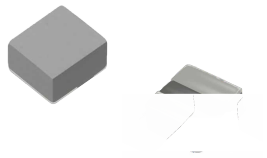
MDTA Series

SMD Low Profile High Current Molded Inductor

Size 160808



FEATURES

- High current, low DCR,
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APPLICATION

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- HVAC
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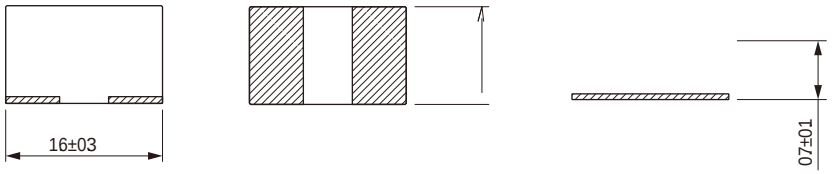
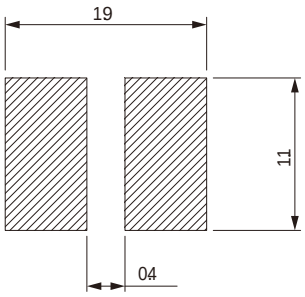
Dimensions: [mm]



Land Pattern: [mm]



Electrical Properties:

	(µH)				Saturation	Saturation	(mΩ)	(mΩ)
MDTA160808-R22M		±20%						40
MDTA160808-R47M		±20%					80	100
		±20%						110
MDTA160808-R68M		±20%						
MDTA160808-1R0M		±20%					180	200

Saturation Current will cause L to drop approximately 30%

Temperature Rise Current: The actual value of DC current when the temperature rise is △T=40°C

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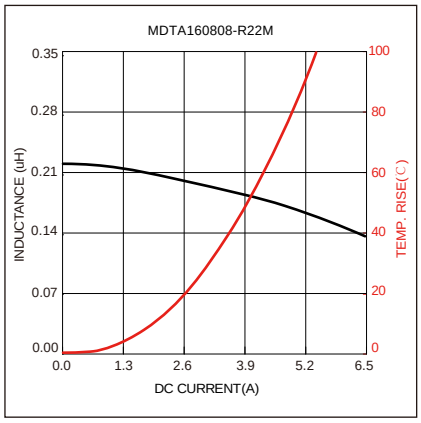
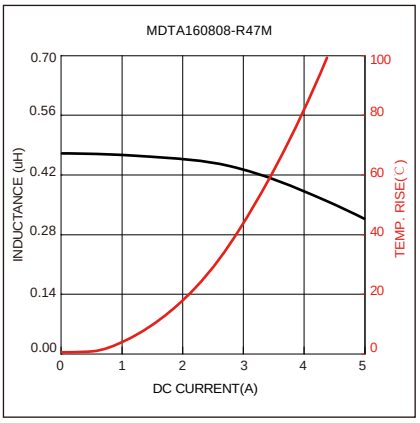
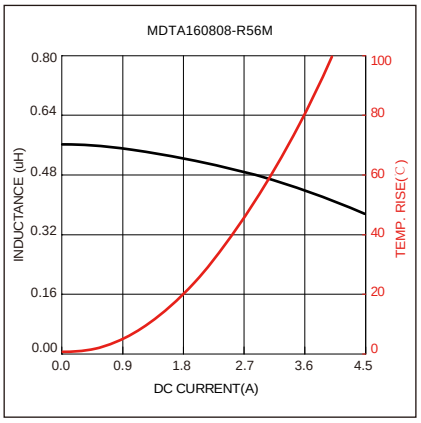
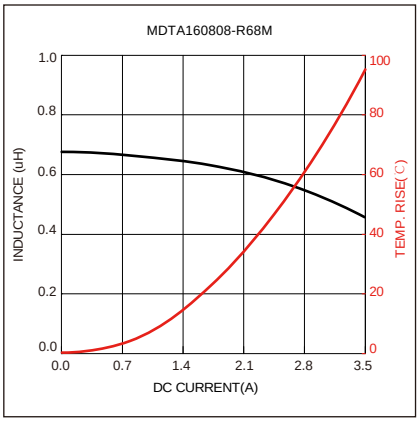
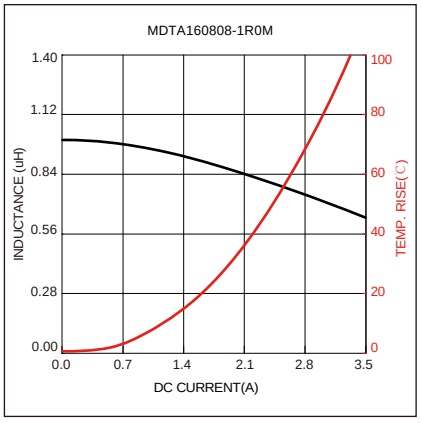
Typical Electrical Characteristics:











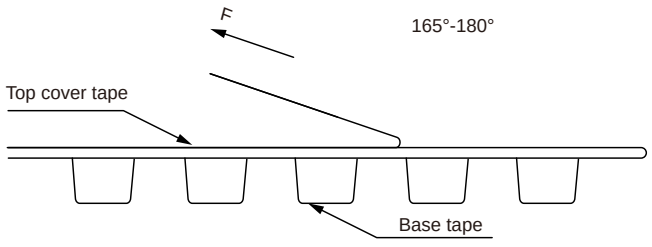
Soldering Reflow:

Packaging Information:

Tape Dimension:

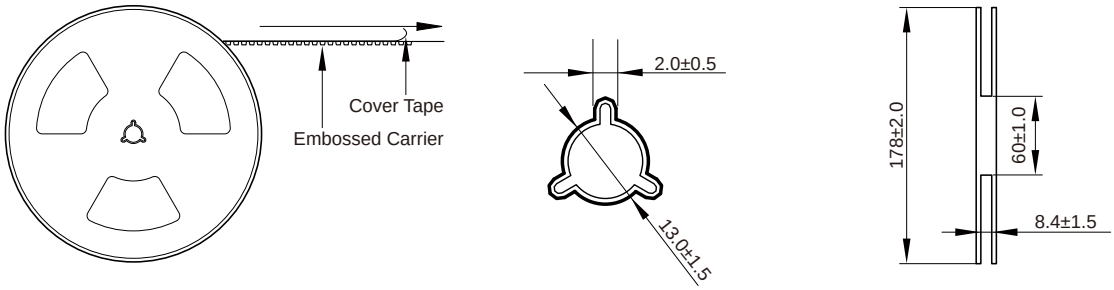
Series	A0 (mm)	B0 (mm)	D (mm)	P0 (mm)	P1 (mm)	W (mm)	K0 (mm)	E (mm)	T (mm)
MDTA160808	1.1±0.1	1.9±0.1	1.5±0.1	4.0±0.1	4.0±0.1	8.0±0.1	1.0±0.1	1.75±0.1	0.25±0.05

Peel force of top cover tape:

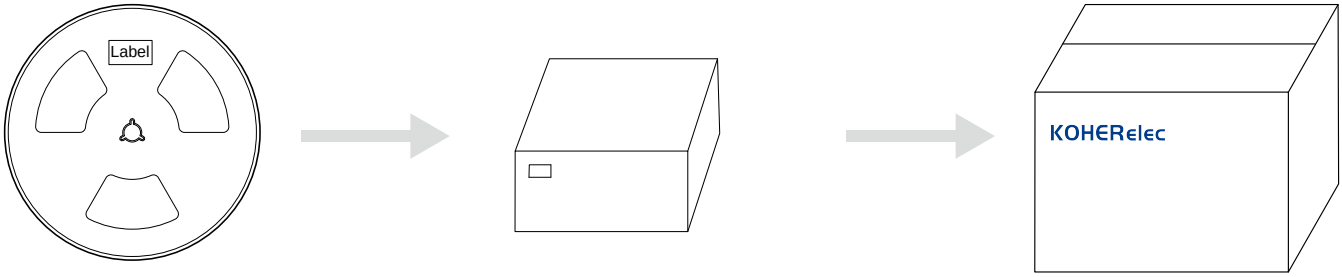


The peel force of top cover tape shall be between 0.1 to 0.98 N

Reel Dimension：[mm]



Packaging Quantity:



3000 Pcs/Reel

5 Reel /Inner box(15K Pcs)

8 Inner box/Carton box(120K Pcs)

Cautions and Warnings:

Storage Conditions：

- The storage period is within 12 months after the completion of production. Be sure to follow the storage conditions (temperature: -5 to 35°C, humidity: 75% RH Max).If the storage period elapses, the soldering of the terminal electrodes may deteriorate.The warranty period is one year.
- Product should not be exposed to environment with high temperature, high humidity, dust, corrosive gas and etc.
- Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
- Please always handle products carefully to prevent any damage caused by dropping down or inappropriate removing.

Operation Instructions:

- Self heating (temperature increase) occurs when the power is turned ON, so the tolerance should be sufficient for the set thermal design.
- Before soldering, be sure to preheat components.The preheating temperature should be set so that the temperature difference between the solder temperature and chip temperature does not exceed 150°C.
- Soldering corrections after mounting should be within the range of the conditions determined in the specifications.If overheated, a short circuit, performance deterioration, or lifespan shortening may occur.
- Generally, Koher might not be familiar with either customer's specific application or actual requests as customer does.As a result customer shall be responsible for checking and confirming whether Koher product with the performance described in the product specification is suitable for using in customer's particular application or not.